

C2220X563K5TACTU

Aliases (C2220X563K5TAC7800) SMD Comm X8G HT150C Flex, Ceramic, 0.056 uF, 10%, 50 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 2220, 3.5 mm



Click here for the 3D model.

General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	130 mg
Shelf Life	78 Weeks
MSL	1

0.056 uF

1 kHz 1.0Vrms

17.8571 GOhms

Dimensions		Specifications
Chip Size	2220	Capacitance
L	5.9mm +/-0.75mm	Measurement Condition
W	5mm +/-0.4mm	Tolerance
т	1mm +/-0.15mm	Voltage DC
S	3.5mm MIN	Dielectric Withstanding V
В	0.7mm +/-0.35mm	Temperature Range
		Temp. Coefficient
Packaging Specifications		Capacitance Change with

5mm +/-0.4mm	Tolerance	10%	
1mm +/-0.15mm	Voltage DC	50 VDC	
3.5mm MIN	Dielectric Withstanding Voltage	125 VDC	
0.7mm +/-0.35mm	Temperature Range	-55/+150°C	
	Temp. Coefficient	X8G	
	Capacitance Change with Reference to +25°C and 0 VDC	30 ppm/C, 1kHz 1.0Vrms	
T&R, 180mm, Plastic Tape	Applied (TCC)		
1000	Dissipation Factor	0.1% 1 kHz 1.0Vrms	
	Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours	

Insulation Resistance

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Packaging

Packaging Quantity